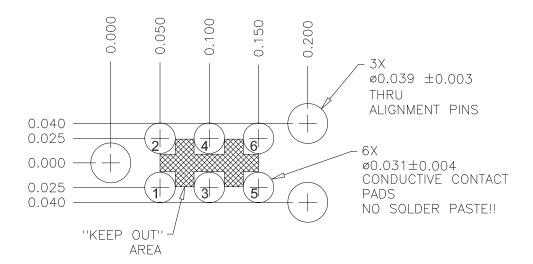
#### Notes

No tracks or vias in the shaded keepout area.

No other track or signal within 0.020" of any contact pad.

Do not allow solder paste on the contact pads. It is essential to eliminate any hole in the solder paste—mask (solder stencil) layer. If this is not possible make the contact pads thru—hole with finished hole size of 0.008" or less.

To avoid ordering confusion, please specify DNL in your BOM.



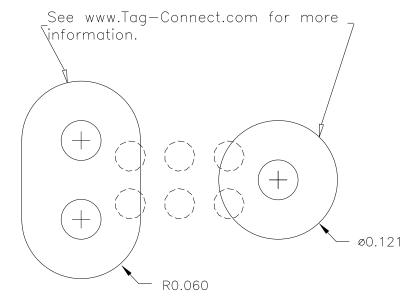
### PCB TOP LAYER

REVISIONS

DESCRIPTION DATE

Optional copper pads allow soldering of s/steel alignment pins to underside of board for debugging use. Use stainless steel soldering flux and care to avoid melting the connector.

Alternatives include the TC2030-CLIP board that grips the s/steel pins from the underside or Mill-Max receptacles P/N 0295-0-15-XX-06-XX-10-0



# OPTIONAL BOTTOM LAYER ALTERNATIVE - USE TC2030 CLIP BOARD

SIZE

SHEET 1 OF 1

Microchip ICD/ICSP Signals

Pin 1: -MCLR/Vpp

Pin 2: Vdd Pin 3: Ground

Pin 4: PGD (ICSPDAT) Pin 5: PGC (ICSPCLK)

Pin 6: Unused or LVP

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DWG. NO.

TC2030-MCP-NL-FP
FOOTPRINT FOR TC2030-MCP-NL

CUSTOMER:

F.

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